### IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: CATABAY et al.

Attorney Docket No.: 01-471/1D / LSI1P172D1

Application No.: Filed Herewith

Examiner: Unassigned

Filed: Herewith

Group: Unassigned

Title: MULTI-STEP PROCESS FOR FORMING A BARRIER FILM FOR USE IN COPPER LAYER

**FORMATION** 

CERTIFICATE OF EXPRESS MAILING

I hereby certify that this paper and the documents and/or fees referred to as attached therein are being deposited with the United States Postal Service on February 3, 2004 in an envelope as "Express Mail Post Office to Addressee" service under 37 CFR §1.10, Mailing Label Number ER562285933US, addressed to: Mail Stop Patent Application, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Sue Funchess

## INFORMATION DISCLOSURE STATEMENT 37 CFR §§1.56 AND 1.97(b)

Mail Stop Patent Application Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

The references listed in the attached PTO Form 1449 may be material to examination of the above-identified patent application. Applicants submit the list of these references in compliance with their duty of disclosure pursuant to 37 CFR §§1.56 and 1.97. The Examiner is requested to make these references of official record in this application. The above-identified application is a divisional application of prior application U.S. Patent Application No. 10/035,704. This prior application is being relied upon for an earlier filing date under 35 U.S.C. § 120. Because the listed references were either cited by the PTO, or submitted to the PTO in the prior application, under 37 CFR § 1.98(d) Applicants submit that copies need not be provided.

This Information Disclosure Statement is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that these references indeed constitute prior art.

This Information Disclosure Statement is: (i) filed within three (3) months of the filing date of the above-referenced application, (ii) believed to be filed before the mailing date of a first Office Action on the merits, or (iii) believed to be filed before the mailing of a first Office Action after the filing of a Request for Continued Examination under §1.114. Accordingly, it is believed that no fees are due in connection with the filing of this Information Disclosure Statement. However, if it is determined that any fees are due, the Commissioner is hereby authorized to charge such fees to Deposit Account 12-2252 (Order No. 01-471/1D).

Respectfully submitted, BEYER WEAVER & THOMAS, LLP

Francis T. Kalinski II Registration No. 44,177

P.O. Box 778 Berkeley, CA 94704-0778

# Form 1449 (Modified) Atty Docket No. Application No.: 01-471/1D / LSI1P172D1 Filed Herewith Applicant: CATABAY et al. Filing Date Group (Use Several Sheets if Necessary) Herewith Unassigned

#### **U.S. Patent Documents**

Examine	er						Sub-	Filing
Initial	¥5.	No.	Patent No.	Date	Patentee	Class	class	Date
		Α	5,925,415	07/20/99	Fry et al.	427	304	03/09/98
		В	6,010,962	01/04/00	Liu et al.	438	687	02/12/99
	•	С	6,015,749	01/18/00	Liu et al.	438	628	05/04/98
		D	6,022,808	02/08/00	Nogami et al.	438	694	03/16/98
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		F	6,042,889	03/28/00	Ballard et al.	427	305	02/28/94
		G	6,066,892	05/23/00	Ding et al.	257	751	05/14/98
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		I	6,235,406	05/22/01	Uzoh	428	620	07/13/00

Foreign Patent or Published Foreign Patent Application

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Examiner		Document	Publication	Country or		Sub-	Trans	lation
Initial	No.	No.	Date	Patent Office	Class	class	Yes	No
	J							
N76	K							
	L							
	M							
	N							

#### **Other Documents**

Examiner					
Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication			
	0	Wolfe, et al., Silicon Processing for the VLSI Era, Vol. 1 – Process			
		Technology, 2 <sup>nd</sup> Ed., Lattice Press: Sunset Beach, CA, 2000, pp. 791-795.			
	P	J.S. Patent Application No. 10/035,705, "Electroless Deposition of Copper to Form Copper Interconnect Structures", filed 10/18/01.			
	Q				
Examiner	1	Date Considered			

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Form 1449 (Modified)	Atty Docket No.	Application No.:
	01-471/1D / LSI1P172D1	Filed Herewith
Information Disclosure	Applicant:	
Statement By Applicant	CATABAY et al.	
	Filing Date	Group
(Use Several Sheets if Necessary)	Herewith	Unassigned

**U.S. Patent Documents** 

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Initial	No.	Patent No.	Date	Patentee	Class	class	Date
	AA	6,255,192B1	07/03/01	Dornisch	438	430	09/09/98
	BB	6,268,291B1	07/31/01	Andricacos et al.	438	694	12/03/98
	CC	6,287,968B1	09/11/01	Yu et al.	438	675	01/04/99
	DD	6,297,158B1	10/02/01	Liu et al.	438	687	05/31/00
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	II	6,429,121B1	08/06/02	Hopper et al.	438	686	02/07/01

Foreign Patent or Published Foreign Patent Application

Examiner		Document	Publication			Sub-	Trans	slation
Initial	No.	No.	Date	Patent Office	Class	class	Yes	No
	JJ							
	KK							
	LL							
	MM							
	NN							

#### **Other Documents**

Examiner		
Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	00	
	PP	
	QQ	
Examiner		Date Considered

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(Use Several Sheets if Necessary)	Herewith	Unassigned

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Initial	No.	Patent No.	Date	Patentee	Class	class	Date
	AAA	6,440,849B1	08/27/02	Merchant et al.	438	658	10/18/99
	BBB	6,445,070B1	09/03/02	Wang et al.	257	751	01/29/01
	CCC	6,461,675B2	10/08/02	Paranjpe et al.	427	250	07/10/98
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	EEE						
	FFF						
	GGG						
	ННН						
	III						

Foreign Patent or Published Foreign Patent Application

Examiner		Document	Publication	Country or		Sub-	Trans	lation
Initial	No.	No.	Date	Patent Office	Class	class	Yes	No
	JJJ							
	KKK							
	LLL							
	MMM							
	NNN							

#### **Other Documents**

Examiner		
Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
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	QQQ	
Examiner		Date Considered

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